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RESPONSE UNDER 37 C.F.R. 1.116
EXPEDITING PROCEDURE
EXAMINING GROUP (1765)

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: HENNHÖFER ET AL.

SERIAL NO.: 09/032,305

EXAMINER: R. KUNEMUND

FILED: FEBRUARY 27, 1998

GROUP: 1765

TITLE: PROCESS FOR TREATING A POLISHED SEMICONDUCTOR
WAFER IMMEDIATELY AFTER THE SEMICONDUCTOR WAFER
HAS BEEN POLISHED

AMENDMENT IN RESPONSE TO FINAL OFFICE ACTION

ATT: BOX AF
Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Final Office Action dated August 7, 2001,
please amend the above-identified patent application as follows:

IN THE CLAIMS:

Please amend claims 14, 17 and 18 as set forth in the Clean
Copy of Amended Claims as follows. Also enclosed is a Marked-up
Version of Amended Claims 14, 17 and 18.

14. (Twice Amended) Process for treating a semiconductor
wafer, comprising
polishing the semiconductor wafer;
immediately after polishing the semiconductor wafer

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TC 1700